/ Descriptions

Silicon NPN transistor in a SOT-23 Plastic Package.

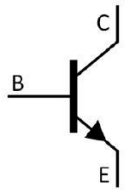
/ Features

High Collector-Emitter Voltage.

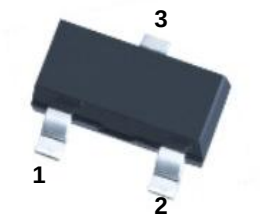
/ Applications

High voltage application.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Emitter PIN 3 Collector

/ h_{FE} Classifications & Marking

h_{FE} Range	30~200
Marking	3DH

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	350	V
Collector to Emitter Voltage	V_{CEO}	350	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current	I_C	500	mA
Collector Power Dissipation	P_C	300	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55～150	

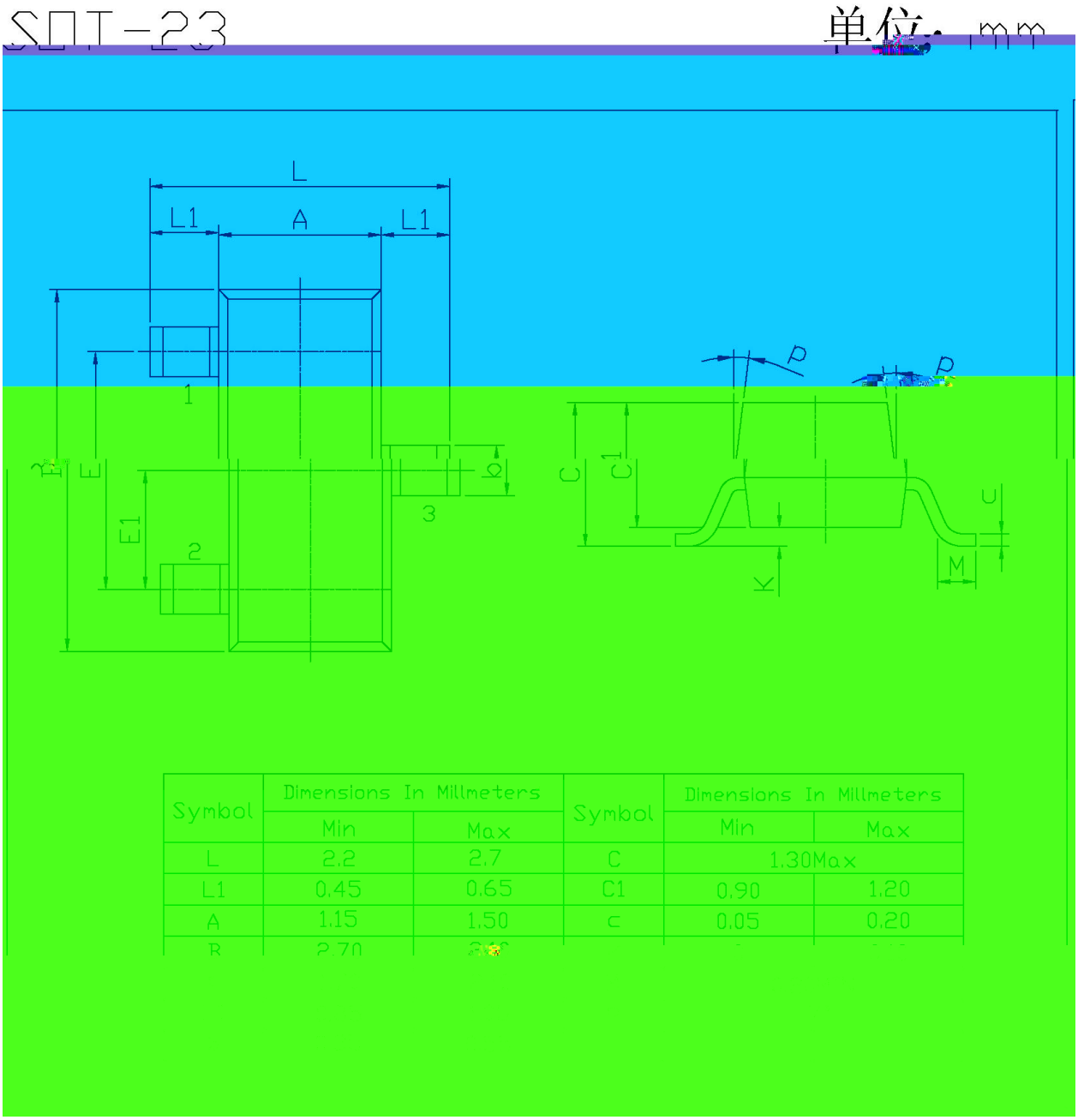
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	I_C=100 A I_E=0	350			V
Collector to Emitter Breakdown Voltage	*V_{CEO}	I_C=1.0mA I_B=0	350			V
Emitter to Base Breakdown Voltage	V_{EBO}	I_E=10 A I_C=0	6.0			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=250V I_E=0			0.05	A
Emitter Cut-Off Current	I_{EBO}	V_{EB}=4.0V I_C=0			0.05	A
DC Current Gain	$h_{FE(1)}$	V_{CE}=10V I_C=30mA	30		200	
	*$h_{FE(2)}$	V_{CE}=10V I_C=100mA	15			
	$h_{FE(3)}$	V_{CE}=10V I_C=1.0mA	20			
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	I_C=10mA I_B=1.0mA			0.3	V
	$V_{CE(sat)}$	I_C=50mA I_B=5.0mA			1.0	V
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	I_C=10mA I_B=1.0mA			0.75	V
	$V_{BE(sat)}$	I_C=30mA I_B=3.0mA			0.9	V
Base–Emitter On Voltage	*$V_{BE(ON)}$	V_{CE}=10V I_C=100mA			2.0	V
Transition Frequency	f_T	V_{CE}=20V I_C=10mA f=20MHz	40		200	MHz
Collector Output Capacitance	C_{ob}	V_{CB}=20V I_E=0 f=1MHz			6.0	pF

*pulse test: pulse width 300 S,duty cycle 2.0%.

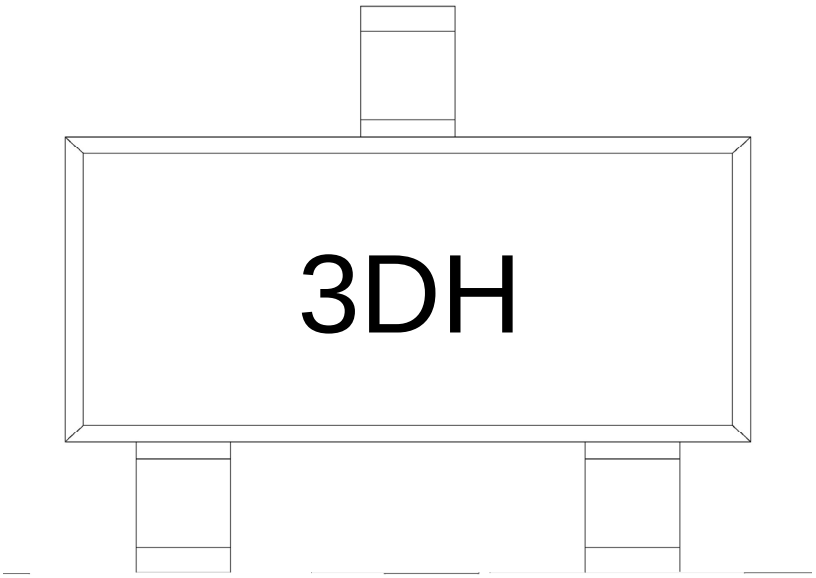
2N6517M

/ Package Dimensions



Symbol	Dimensions In Millmeters		Symbol	Dimensions In Millmeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
R	2.70				

/ Marking Instructions

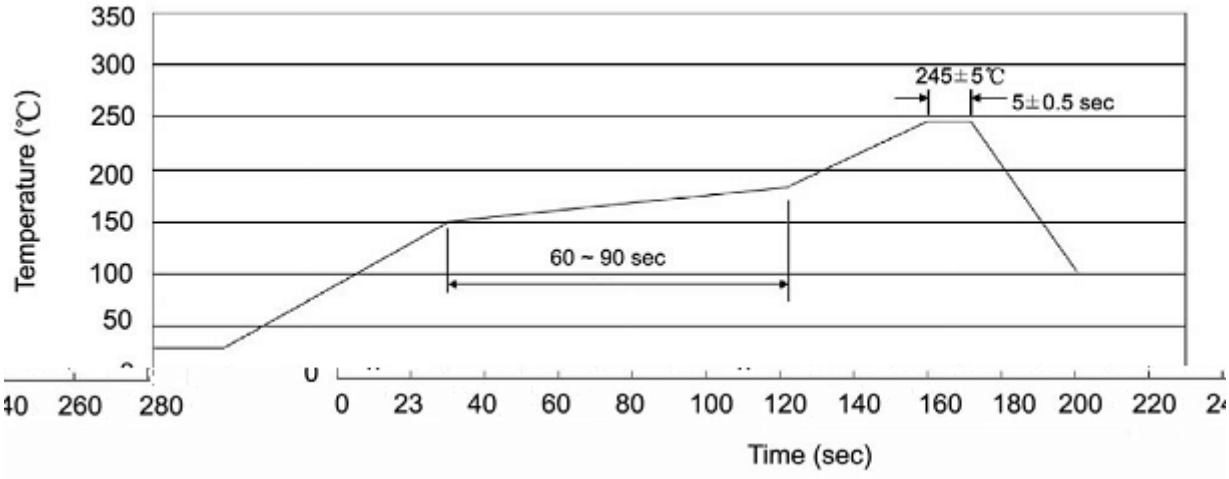


Note:

Product Type Code

Company Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 25 150 60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2 245 5 5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec.	Temp.:260 5 Time:10 1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
						〃		

/ Notices